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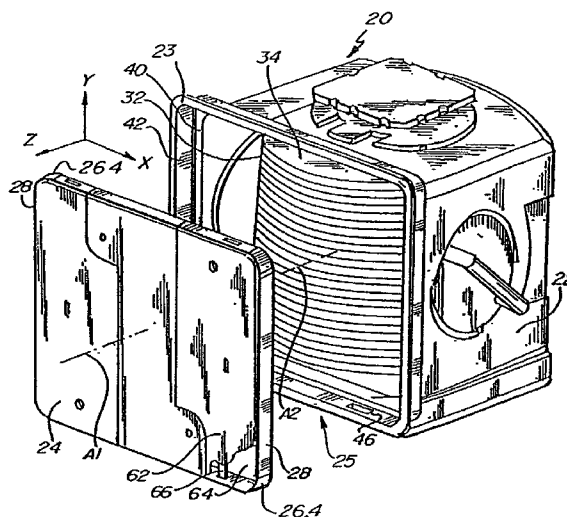
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- (74) Agents: **CHRISTENSEN, Douglas, J.** et al.; Patterson, Thunte, Skaar & Christensen, P.A., 4800 IDS Center, 80 South Eighth Street, Minneapolis, MN 55402-2100 (US).
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- (71) Applicant (for all designated States except US): **ENTEGRIS, INC.** [US/US]; 3500 Lyman Boulevard, Chaska, MN 55318 (US).
- (72) Inventor; and
- (75) Inventor/Applicant (for US only): **EGGUM, Shawn, D.** [US/US]; 6823 Jackson Avenue, Lonsdale, MN 55046 (US).
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(54) Title: WAFER ENCLOSURE SEALING ARRANGEMENT FOR WAFER CONTAINERS



(57) Abstract: A wafer container (20) comprises a housing (22) with a door frame (23), defining an opening (25) for insertion and removal of wafers, and a door (24) for insertion into the door frame (23). The door (24) includes a wafer enclosure sealing arrangement (50) for hermetically sealing the door (24) with the door frame (23) of the housing (22). The wafer enclosure sealing arrangement (50) includes a first groove (52) disposed about a perimeter of the interior surface of the door (24) and a second groove (54) disposed adjacent to the first groove and spaced laterally from the perimeter of the door (24). The sealing arrangement (50) includes a support member (53) disposed between the first and second grooves (52, 54). The sealing arrangement (50) also includes an elastomeric seal member (26) having a first portion (26.1) that is frictionally inserted into the second groove (54) and extends around the door (24) and a second portion (26.6) that cantilevers downward into the second groove (54) when the door (24) and housing (22) are joined.



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